BUK7610-100B

N-channel TrenchMOS standard level FET

6 July 2012 **Product data sheet**

1. Product profile

1.1 General description

Standard level N-channel enhancement mode Field-Effect Transistor (FET) in a plastic package using TrenchMOS technology. This product has been designed and qualified to the appropriate AEC standard for use in automotive critical applications.

1.2 Features and benefits

- Low conduction losses due to low on-state resistance
- Q101 compliant
- Suitable for standard level gate drive sources
- Suitable for thermally demanding environments due to 175 °C rating

1.3 Applications

- 12 V, 24 V and 42 V loads
- Automotive systems
- General purpose power switching
- Motors, lamps and solenoids

1.4 Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25$ °C; $T_j \leq 175$ °C		-	-	100	V
I_D	drain current	$V_{GS} = 10$ V; $T_{mb} = 25$ °C; Fig. 1; Fig. 3	[1]	-	-	75	A
P_{tot}	total power dissipation	$T_{mb} = 25$ °C; Fig. 2		-	-	300	W
Static characteristics							
R_{DSon}	drain-source on-state resistance	$V_{GS} = 10$ V; $I_D = 25$ A; $T_j = 25$ °C; Fig. 11; Fig. 12		-	8.6	10	mΩ
Dynamic characteristics							
Q_{GD}	gate-drain charge	$V_{GS} = 10$ V; $I_D = 25$ A; $V_{DS} = 80$ V; $T_j = 25$ °C; Fig. 13		-	22	-	nC
Avalanche ruggedness							
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$I_D = 75$ A; $V_{sup} \leq 100$ V; $R_{GS} = 50$ Ω; $V_{GS} = 10$ V; $T_{j(init)} = 25$ °C; unclamped		-	-	629	mJ

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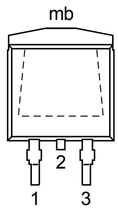
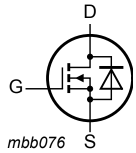
[1] Continuous current is limited by package.

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate	 **D2PAK (SOT404)**	
2	D	drain[1]		
3	S	source		
mb	D	mounting base; connected to drain		

[1] It is not possible to make connection to pin 2.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BUK7610-100B	D2PAK	plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)	SOT404

4. Marking

Table 4. Marking codes

Type number	Marking code
BUK7610-100B	BUK7610-100B

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DS}	drain-source voltage	$T_j \geq 25$ °C; $T_j \leq 175$ °C		-	100	V
V_{DGR}	drain-gate voltage	$R_{GS} = 20$ kΩ		-	100	V
V_{GS}	gate-source voltage			-20	20	V
I_D	drain current	$T_{mb} = 25$ °C; $V_{GS} = 10$ V; Fig. 1; Fig. 3	[1]	-	110	A
			[2]	-	75	A
		$T_{mb} = 100$ °C; $V_{GS} = 10$ V; Fig. 1	[2]	-	75	A
I_{DM}	peak drain current	$T_{mb} = 25$ °C; pulsed; $t_p \leq 10$ μs; Fig. 3		-	438	A

Symbol	Parameter	Conditions		Min	Max	Unit
P_{tot}	total power dissipation	T_{mb} = 25 °C; Fig. 2		-	300	W
T_{stg}	storage temperature			-55	175	°C
T_j	junction temperature			-55	175	°C
Source-drain diode						
I_S	source current	T_{mb} = 25 °C	[1]	-	110	A
			[2]	-	75	A
I_{SM}	peak source current	pulsed; t_p ≤ 10 µs; T_{mb} = 25 °C		-	438	A
Avalanche ruggedness						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	I_D = 75 A; V_{sup} ≤ 100 V; R_{GS} = 50 Ω; V_{GS} = 10 V; $T_{j(init)}$ = 25 °C; unclamped		-	629	mJ

[1] Current is limited by power dissipation chip rating.
[2] Continuous current is limited by package.

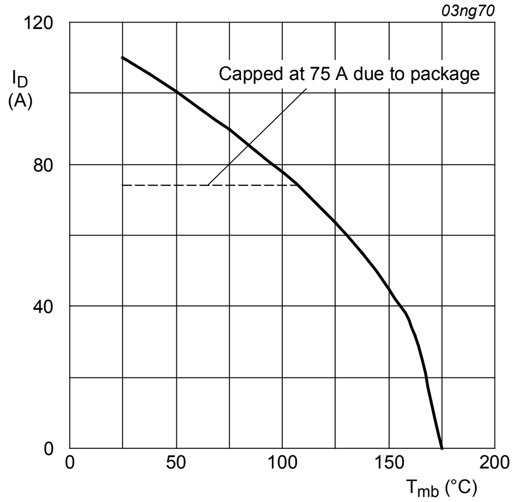


Fig. 1. Normalized continuous drain current as a function of mounting base temperature

$$V_{GS} \geq 5\ V$$

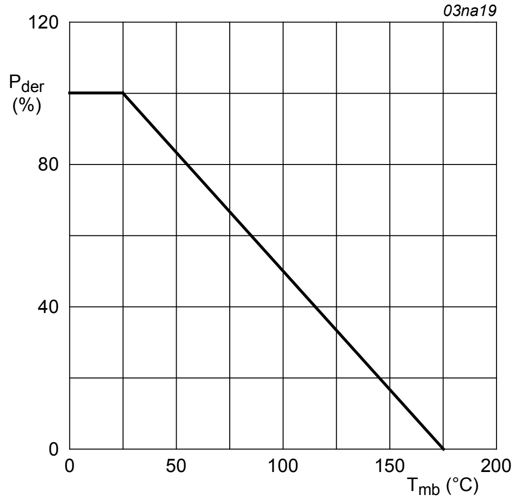


Fig. 2. Normalized total power dissipation as a function of mounting base temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\ \%$$

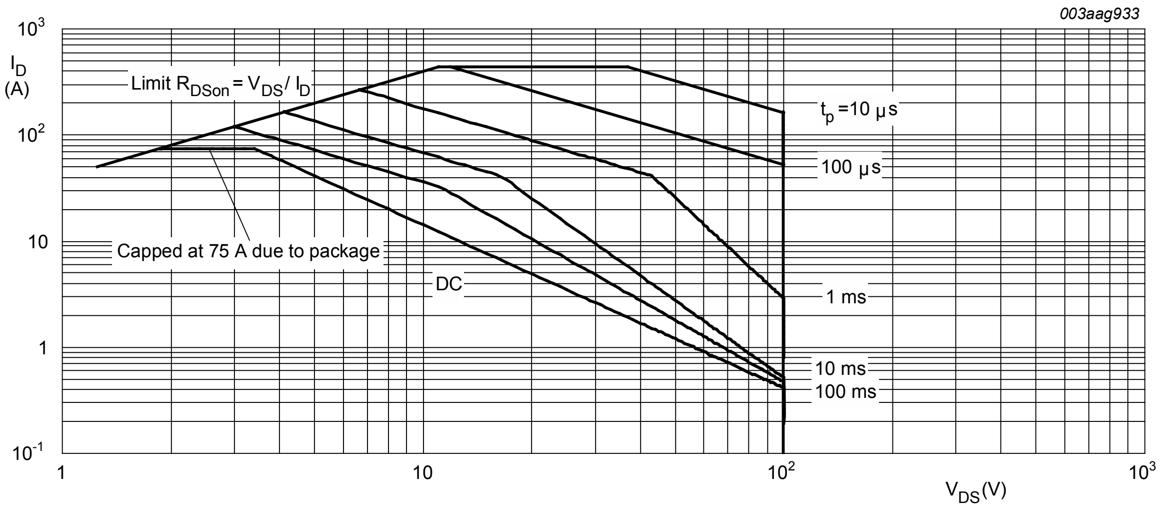


Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

$T_{mb} = 25°C$; I_{DM} is a single pulse

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 4		-	-	0.5	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	mounted on printed-circuit board ; minimum footprint		-	50	-	K/W

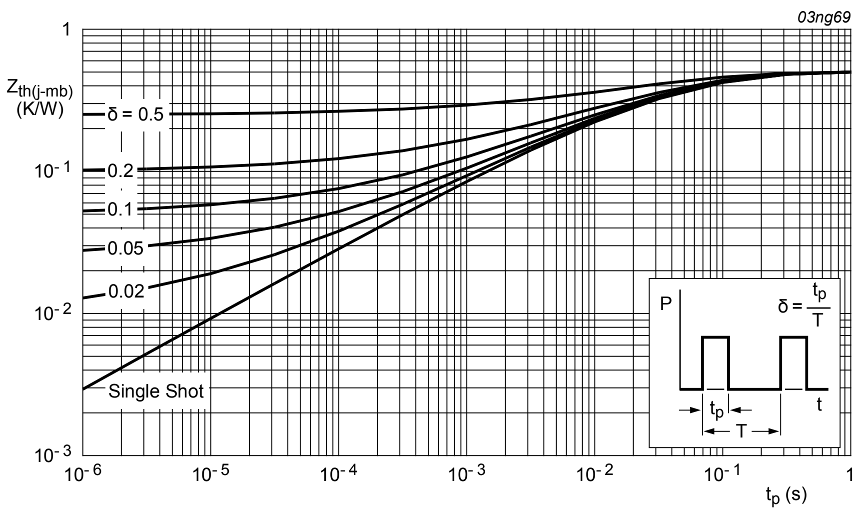


Fig. 4. Transient thermal impedance from junction to mounting base as a function of pulse duration

7. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
$V_{(BR)DSS}$	drain-source breakdown voltage	I_D = 0.25 mA; V_{GS} = 0 V; T_j = 25 °C		100	-	-	V
		I_D = 0.25 mA; V_{GS} = 0 V; T_j = -55 °C		89	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	I_D = 1 mA; V_{DS} = V_{GS}; T_j = 175 °C; Fig. 10		1	-	-	V
		I_D = 1 mA; V_{DS} = V_{GS}; T_j = 25 °C; Fig. 10		2	3	4	V
		I_D = 1 mA; V_{DS} = V_{GS}; T_j = -55 °C; Fig. 10		-	-	4.4	V
I_{DSS}	drain leakage current	V_{DS} = 100 V; V_{GS} = 0 V; T_j = 25 °C		-	0.02	1	µA
		V_{DS} = 100 V; V_{GS} = 0 V; T_j = 175 °C		-	-	500	µA
I_{GSS}	gate leakage current	V_{GS} = 20 V; V_{DS} = 0 V; T_j = 25 °C		-	2	100	nA
		V_{GS} = -20 V; V_{DS} = 0 V; T_j = 25 °C		-	2	100	nA
R_{DSon}	drain-source on-state resistance	V_{GS} = 10 V; I_D = 25 A; T_j = 25 °C; Fig. 11; Fig. 12		-	8.6	10	mΩ
		V_{GS} = 10 V; I_D = 25 A; T_j = 175 °C; Fig. 11; Fig. 12		-	-	25	mΩ
Dynamic characteristics							
$Q_{G(tot)}$	total gate charge	I_D = 25 A; V_{DS} = 80 V; V_{GS} = 10 V; T_j = 25 °C; Fig. 13		-	80	-	nC
Q_{GS}	gate-source charge			-	18	-	nC
Q_{GD}	gate-drain charge			-	22	-	nC
C_{iss}	input capacitance	V_{GS} = 0 V; V_{DS} = 25 V; f = 1 MHz; T_j = 25 °C; Fig. 14		-	5080	6773	pF
C_{oss}	output capacitance			-	677	812	pF
C_{rss}	reverse transfer capacitance			-	168	230	pF
$t_{d(on)}$	turn-on delay time	V_{DS} = 30 V; R_L = 1.2 Ω; V_{GS} = 10 V; $R_{G(ext)}$ = 10 Ω; T_j = 25 °C		-	33	-	ns
t_r	rise time			-	45	-	ns
$t_{d(off)}$	turn-off delay time			-	120	-	ns
t_f	fall time			-	36	-	ns
L_D	internal drain inductance	from drain lead 6 mm from package to centre of die ; T_j = 25 °C		-	4.5	-	nH
		from upper edge of drain mounting base to centre of die ; T_j = 25 °C		-	2.5	-	nH
L_S	internal source inductance	from source lead to source bond pad ; T_j = 25 °C		-	7.5	-	nH

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Source-drain diode							
V_{SD}	source-drain voltage	I_S = 40 A; V_{GS} = 0 V; T_j = 25 °C; Fig. 15		-	0.85	1.2	V
t_{rr}	reverse recovery time	I_S = 20 A; dI_S/dt = -100 A/µs; V_{GS} = -10 V; V_{DS} = 30 V; T_j = 25 °C		-	69	-	ns
Q_r	recovered charge			-	212	-	nC

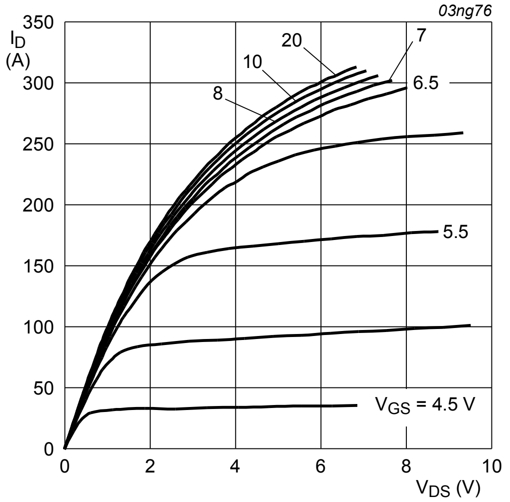


Fig. 5. **Output characteristics: drain current as a function of drain-source voltage; typical values**

$T_j = 25°C; t_p = 300\mu s$

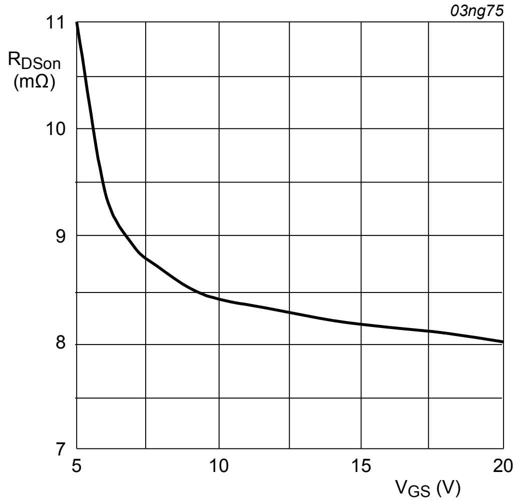


Fig. 6. **Drain-source on-state resistance as a function of gate-source voltage; typical values**

$T_j = 25°C; I_D = 25A$

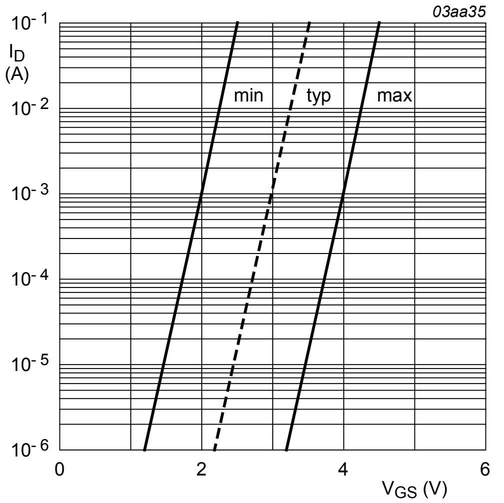


Fig. 7. **Sub-threshold drain current as a function of gate-source voltage**

$T_j = 25°C; V_{DS} = 5V$

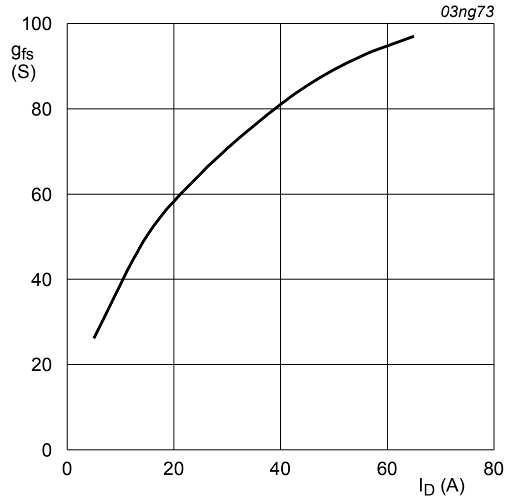


Fig. 8. **Forward transconductance as a function of drain current; typical values**

$T_j = 25°C; V_{DS} = 25V$

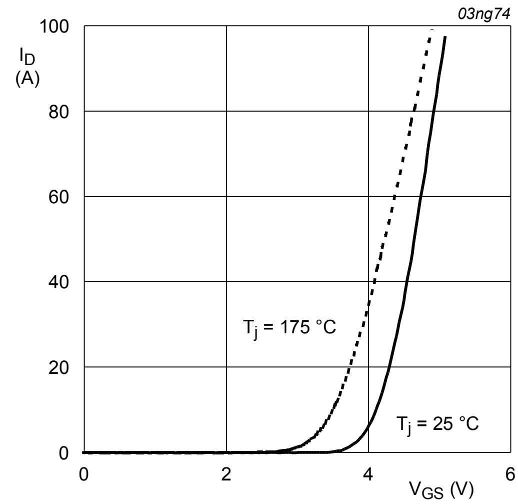


Fig. 9. Transfer characteristics: drain current as a function of gate-source voltage; typical values

$$V_{DS} = 25V$$

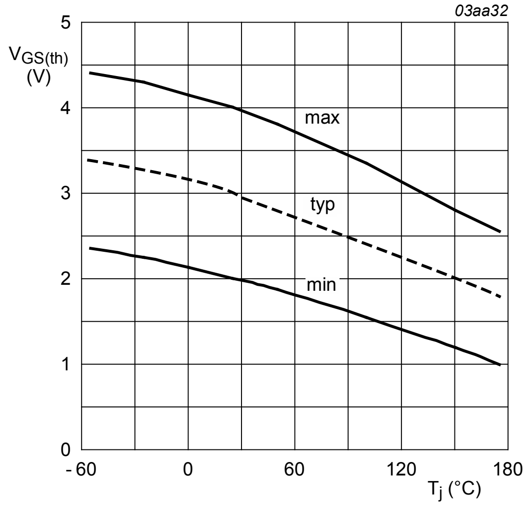


Fig. 10. Gate-source threshold voltage as a function of junction temperature

$$I_D = 1mA; V_{DS} = V_{GS}$$

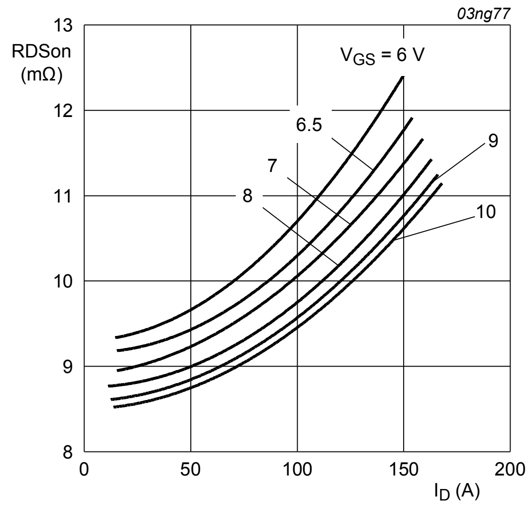


Fig. 11. Drain-source on-state resistance as a function of drain current; typical values

$$T_j = 25°C$$

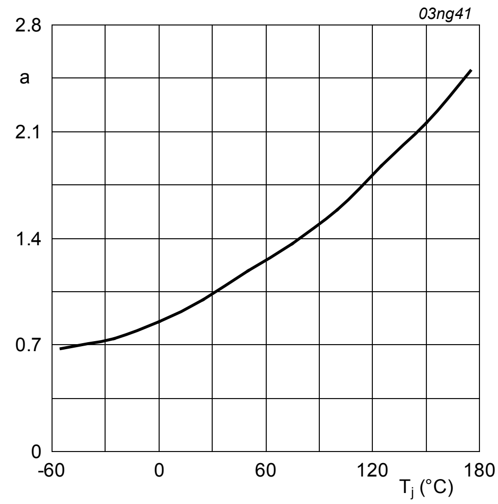


Fig. 12. Normalized drain-source on-state resistance factor as a function of junction temperature

$$a = \frac{R_{DSon}}{R_{DSon(25°C)}}$$

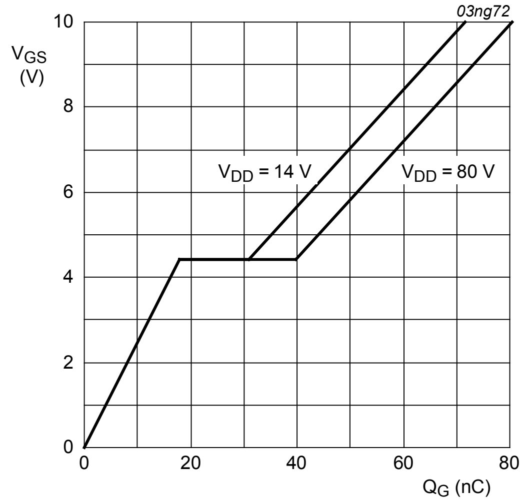


Fig. 13. Gate-source voltage as a function of gate charge; typical values

$T_j = 25°C; I_D = 25A$

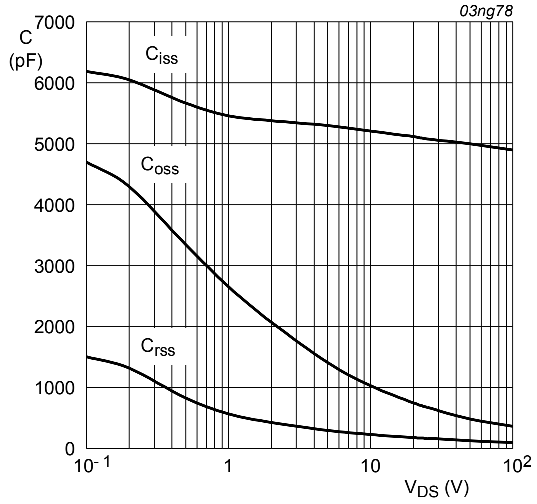


Fig. 14. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

$V_{GS} = 0V; f = 1MHz$

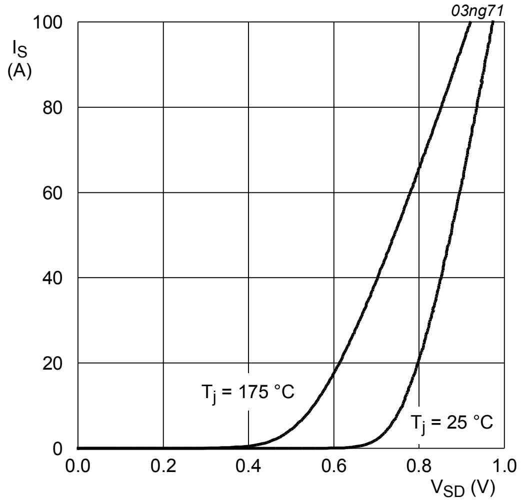
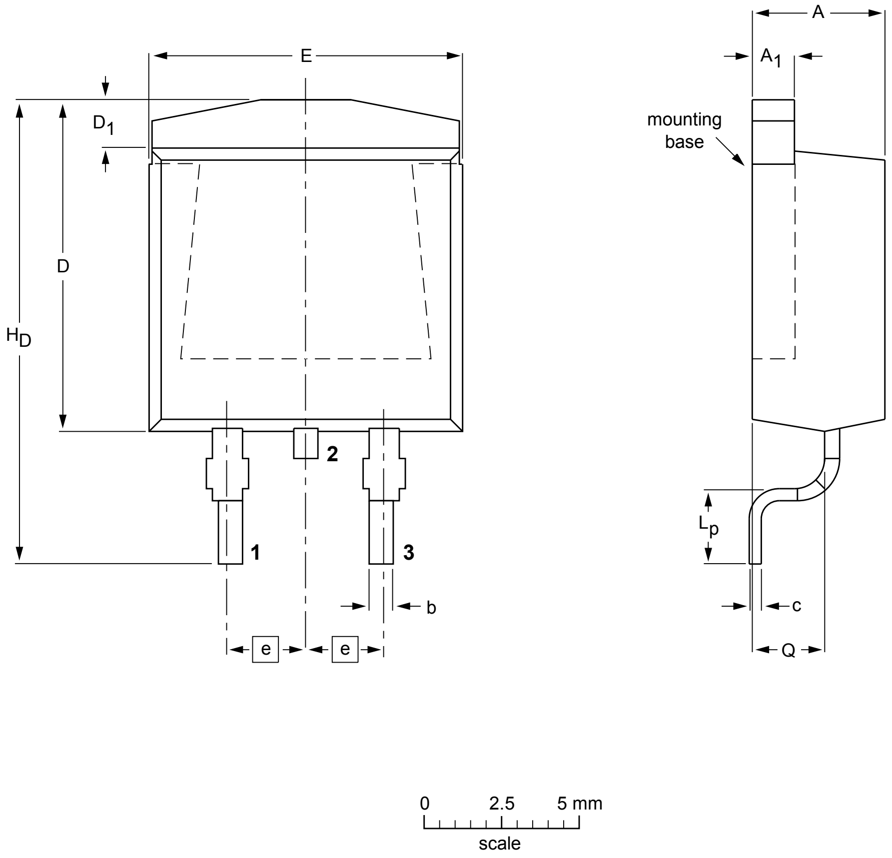


Fig. 15. Reverse diode current as a function of reverse diode voltage; typical value

$V_{GS} = 0V$

8. Package outline

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped) **SOT404**



DIMENSIONS (mm are the original dimensions)

UNIT	A	A_1	b	c	D max.	D_1	E	e	L_p	H_D	Q
mm	4.50 4.10	1.40 1.27	0.85 0.60	0.64 0.46	11	1.60 1.20	10.30 9.70	2.54	2.90 2.10	15.80 14.80	2.60 2.20

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT404						~~05-02-11~~ 06-03-16

Fig. 16. D2PAK (SOT404)

9. Legal information

9.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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